NASA TECH BRIEF

NASA Pasadena Office



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Magnet-Wire Wrapping Tool for Integrated Circuits

The problem:

To wrap magnet wire around integrated-circuit terminals uniformly and securely without damaging the insulative coating on the wire.

The solution:

A wire-dispensing tool which resembles a mechanical pencil.

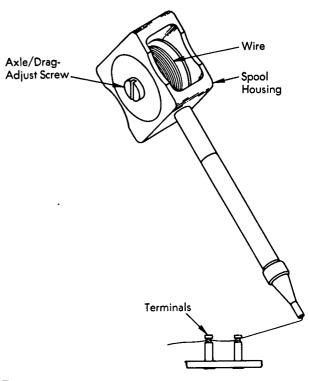
How it's done:

The tool shown in the diagram carries a supply of magnet wire on a spool. The wire passes through the hollow pencil-like stem and then through a tip of small diameter. The tool is manipulated easily inasmuch as it fits in the hand like a pencil; the tip is readily made to execute wire-wrapping movements. The tightness of the wire wrap is controlled by tension on the wire; the tension is controlled by restricting the unwinding of the wire from the spool by means of friction controlled by a screw on the axle supporting the spool.

Note:

Requests for further information may be directed

Technology Utilization Officer NASA Pasadena Office 4800 Oak Grove Drive Pasadena, California 91103 Reference: TSP 72-10426



Patent status:

No patent action is contemplated by NASA.

Source: Ted H. Takahashi of Caltech/IPL under contract to NASA Pasadena Office

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